SMT power inductors

Size 10.4 × 10.4 × 4.8 (mm)

Series/Type: B82464G4
Date: October 2019
SMT power inductors B82464G4
Size 10.4 x 10.4 x 4.8 (mm)

Rated inductance 0.82 ... 1000 μH
Rated current 0.34 ... 7.6 A

Construction
- Ferrite core
- Magnetically shielded
- Winding: enamel copper wire
- Winding welded to terminals

Features
- Temperature range up to +150 °C
- High rated current
- Low DC resistance
- Suitable for lead-free reflow soldering as referenced in JEDEC J-STD 020D
- Qualified to AEC-Q200
- RoHS-compatible

Applications
- Filtering of supply voltages
- Coupling, decoupling
- DC/DC converters
- Automotive electronics
- Industrial electronics

Terminals
- Base material CuFe2P
- Layer composition Ag, Sn (lead-free)
- Electro-plated

Marking
- Marking on component:
  - Manufacturer, L value (nH, coded),
  - L tolerance (coded), manufacturing date (YWWD),
  - two last digits of work order
- Minimum data on reel:
  - Manufacturer, ordering code,
  - L value, quantity, date of packing

Delivery mode and packing unit
- 16-mm blister tape, wound on 330-mm Ø reel
- Packing unit: 750 pcs./reel

Please read Cautions and warnings and Important notes at the end of this document.
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SMD

Dimensional drawing and layout recommendation

1) Soldering area

Taping and packing

Blister tape

Reel

Dimensions in mm

Please read Cautions and warnings and Important notes at the end of this document.
### Technical data and measuring conditions

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Specification</th>
</tr>
</thead>
<tbody>
<tr>
<td>Rated inductance $L_R$</td>
<td>Measured with impedance analyzer Agilent 4294A or equivalent at frequency $f_L$, 0.1 V, +20 °C</td>
</tr>
<tr>
<td>Operating temperature range</td>
<td>$-55 , ^\circ C \ldots +150 , ^\circ C$</td>
</tr>
<tr>
<td>Rated current $I_{\text{temp}}$</td>
<td>Max. permissible DC with temperature increase of $\leq 40$ K at $+85 , ^\circ C$</td>
</tr>
<tr>
<td>Saturation current $I_{\text{sat}}$</td>
<td>Max. permissible DC with inductance decrease $\Delta L/L_0$ of approx. 10%</td>
</tr>
<tr>
<td>DC resistance $R_{\text{max}}$</td>
<td>Measured at $+20 , ^\circ C$</td>
</tr>
<tr>
<td>Solderability (lead-free)</td>
<td>Dip and look method Sn95.5Ag3.8Cu0.7: $+(245 \pm 5) , ^\circ C$, $(5 \pm 0.3)$ s</td>
</tr>
<tr>
<td></td>
<td>Wetting of soldering area $\geq 90%$</td>
</tr>
<tr>
<td></td>
<td>(based on IEC 60068-2-58)</td>
</tr>
<tr>
<td>Resistance to soldering heat</td>
<td>$+260 , ^\circ C$, 40 s (as referenced in JEDEC J-STD 020D)</td>
</tr>
<tr>
<td>Climatic category</td>
<td>55/150/56 (to IEC 60068-1)</td>
</tr>
<tr>
<td>Storage conditions</td>
<td>Mounted: $-55 , ^\circ C \ldots +150 , ^\circ C$</td>
</tr>
<tr>
<td></td>
<td>Packaged: $-25 , ^\circ C \ldots +40 , ^\circ C$, $\leq 75%$ RH</td>
</tr>
<tr>
<td>Weight</td>
<td>Approx. 2 g</td>
</tr>
</tbody>
</table>
### SMT power inductors B82464G4

**Size 10.4 x 10.4 x 4.8 (mm)**

**SMD**

### Characteristics and ordering codes

<table>
<thead>
<tr>
<th>L_R</th>
<th>Tolerance</th>
<th>f_L MHz</th>
<th>I_{sat,typ} A</th>
<th>I_{sat,min} A</th>
<th>I_{temp,typ} A</th>
<th>R_{max} Ω</th>
<th>R_{typ} Ω</th>
<th>Ordering code</th>
</tr>
</thead>
<tbody>
<tr>
<td>0.82</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>13.20</td>
<td>10.30</td>
<td>7.60</td>
<td>0.007</td>
<td>0.0047</td>
<td>B82464G4821M000</td>
</tr>
<tr>
<td>1.0</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>11.00</td>
<td>10.00</td>
<td>7.50</td>
<td>0.007</td>
<td>0.0047</td>
<td>B82464G4102M000</td>
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<tr>
<td>1.5</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>9.81</td>
<td>8.50</td>
<td>7.00</td>
<td>0.009</td>
<td>0.0075</td>
<td>B82464G4152M000</td>
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<tr>
<td>2.2</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>7.90</td>
<td>7.00</td>
<td>6.50</td>
<td>0.010</td>
<td>0.0080</td>
<td>B82464G4222M000</td>
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<tr>
<td>3.3</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>6.88</td>
<td>5.90</td>
<td>5.50</td>
<td>0.012</td>
<td>0.0094</td>
<td>B82464G4332M000</td>
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<tr>
<td>4.7</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>6.22</td>
<td>5.20</td>
<td>4.90</td>
<td>0.015</td>
<td>0.0113</td>
<td>B82464G4472M000</td>
</tr>
<tr>
<td>6.8</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>4.99</td>
<td>4.60</td>
<td>4.30</td>
<td>0.020</td>
<td>0.0151</td>
<td>B82464G4682M000</td>
</tr>
<tr>
<td>10</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>3.80</td>
<td>3.50</td>
<td>3.40</td>
<td>0.030</td>
<td>0.021</td>
<td>B82464G4103M000</td>
</tr>
<tr>
<td>15</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>3.68</td>
<td>3.10</td>
<td>2.75</td>
<td>0.040</td>
<td>0.031</td>
<td>B82464G4153M000</td>
</tr>
<tr>
<td>22</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>2.85</td>
<td>2.50</td>
<td>2.25</td>
<td>0.052</td>
<td>0.045</td>
<td>B82464G4223M000</td>
</tr>
<tr>
<td>33</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>2.34</td>
<td>2.10</td>
<td>1.85</td>
<td>0.075</td>
<td>0.062</td>
<td>B82464G4333M000</td>
</tr>
<tr>
<td>47</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>2.00</td>
<td>1.80</td>
<td>1.55</td>
<td>0.095</td>
<td>0.080</td>
<td>B82464G4473M000</td>
</tr>
<tr>
<td>68</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>1.57</td>
<td>1.45</td>
<td>1.30</td>
<td>0.13</td>
<td>0.116</td>
<td>B82464G4683M000</td>
</tr>
<tr>
<td>100</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>1.30</td>
<td>1.15</td>
<td>1.05</td>
<td>0.22</td>
<td>0.192</td>
<td>B82464G4104M000</td>
</tr>
<tr>
<td>150</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>1.02</td>
<td>0.90</td>
<td>0.85</td>
<td>0.32</td>
<td>0.28</td>
<td>B82464G4154M000</td>
</tr>
<tr>
<td>220</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>0.86</td>
<td>0.75</td>
<td>0.70</td>
<td>0.44</td>
<td>0.39</td>
<td>B82464G4224M000</td>
</tr>
<tr>
<td>330</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>0.80</td>
<td>0.65</td>
<td>0.59</td>
<td>0.65</td>
<td>0.56</td>
<td>B82464G4334M000</td>
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<tr>
<td>470</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>0.61</td>
<td>0.55</td>
<td>0.50</td>
<td>0.93</td>
<td>0.83</td>
<td>B82464G4474M000</td>
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<tr>
<td>680</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>0.48</td>
<td>0.46</td>
<td>0.42</td>
<td>1.30</td>
<td>1.24</td>
<td>B82464G4684M000</td>
</tr>
<tr>
<td>1000</td>
<td>±20% ± M</td>
<td>0.1</td>
<td>0.40</td>
<td>0.35</td>
<td>0.34</td>
<td>2.20</td>
<td>1.93</td>
<td>B82464G4105M000</td>
</tr>
</tbody>
</table>

Please read Cautions and warnings and Important notes at the end of this document.
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Cautions and warnings

■ Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
  – Particular attention should be paid to the derating curves given there.
  – The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.

■ If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation. Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

■ The following points must be observed if the components are potted in customer applications:
  – Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  – It is necessary to check whether the potting material used attacks or destroys the wire, wire insulation, plastics or glue.
  – The effect of the potting material can change the high-frequency behaviour of the components.
  – Many coating materials have a negative effect (chemically and mechanically) on the winding wires, insulation materials and connecting points. Customers are always obligated to determine whether and to what extent their coating materials influence the component.
  – Customers are responsible and bear all risk for the use of the coating material. TDK Electronics does not assume any liability for failures of our components that are caused by the coating material.

■ Ceramics / Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.

■ Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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Release 2018-10